



CSP-41 Lead Free RoHS Profile

Total Mass of the Unit specified (g):	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.029	41 Ball CSP	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	20.87860	715,198	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.01248	427	
		Metalization	UBM	Aluminium (Al)	7429-90-5	0.00775	265	
		Metalization	UBM	Nickel (Ni)	7440-02-0	0.00387	133	
		Metalization	UBM	Vanadium (V)	7440-62-2	0.00387	133	
		Metalization	UBM	Copper (Cu)	7440-50-8	0.03086	1,057	
		Metalization	BCB			0.04688	1,606	Cyclotene 4022-35
		IC Solderball	Solderball	Tin (Sn)	7440-31-5	7.83914	268,530	
		IC Solderball	Solderball	Silver (Ag)	7440-22-4	0.32830	11,246	
		IC Solderball	Solderball	Copper (Cu)	7440-50-8	0.041	1,404	

Total mass (mg)	29.193
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